

SOT172A2

studded ceramic package; 4 leads

8 February 2016

Package information

1. Package summary

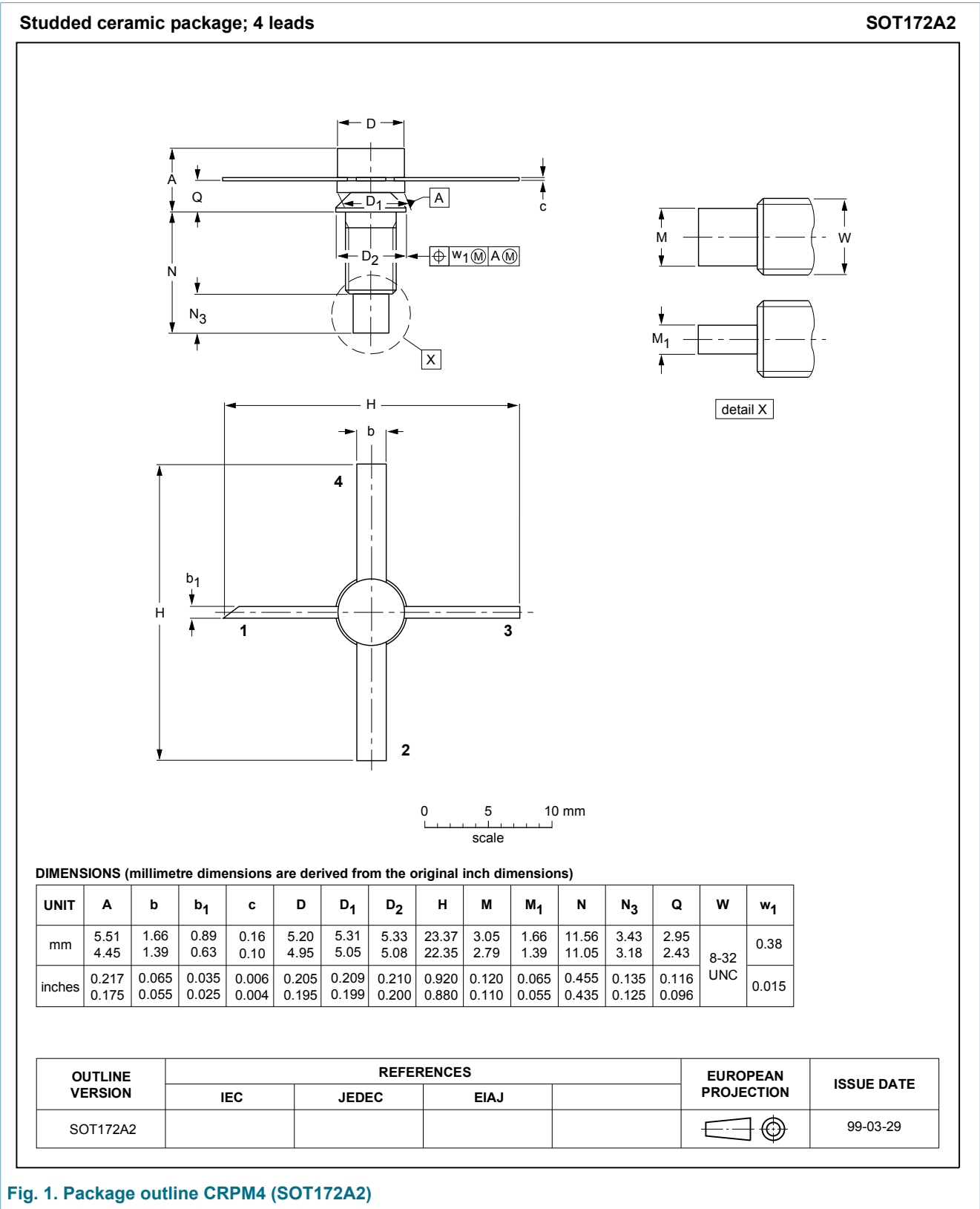
Terminal position code	R (radial)
Package type descriptive code	CRPM4
Package type industry code	CRPM4
Package style descriptive code	CRPM (ceramic radial post (stud) mount)
Package style suffix code	NA (not applicable)
Package body material type	C (ceramic)
Mounting method type	P (post (stud) mount)
Issue date	29-3-1999

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		4.95	-	5.075	5.2	mm
A	seated height		4.45	-	4.98	5.51	mm
n ₂	actual quantity of termination		-	-	4	-	



2. Package outline



3. Legal information

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